

Specification for Approval

Customer: _____

Customer Part No.: _____

Supplier: Fuda Semiconductor (Hefei) Co., Ltd

Spec description: _____

Supplier Part No.: J-FDIMPP

Date: 2023/6/1

Version: A.0

Draw: _____

Supplier Approve		Customer Approve
EE Confirm by	PE Confirm by	
QE Confirm by	Approval by	

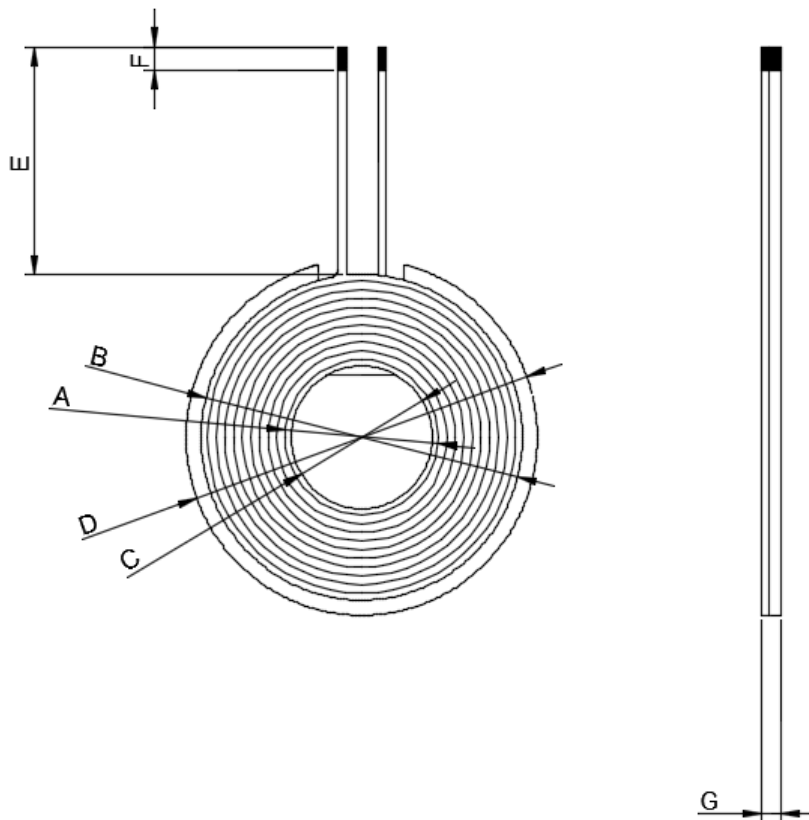
Version Change History

Revision	Before change	After change	Date	Approval by
A.0	—	(Initial Release)	2023/6/1	

1. Manufacturer information

Items	Manufacturer name	Approval
The first resource	GEO	Roger
The second resource		

2. Dimension specification



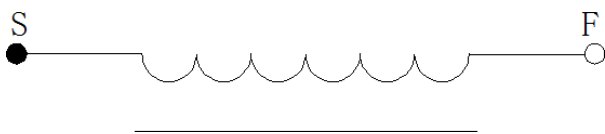
Unit:mm

A	B	C	D	E	F	G
20.5±0.5	39±1	19.5±0.3	42.5±0.5	8±1	4±1.5	2.05±0.1

Note:

- Do not stick high-temperature tape at the coil lead
- When the coil is attached to the magnetic separator, it must not exceed the edge of the separator

3. Schematic diagram



4. Electronic character

TEMPERATURE: $25 \pm 10^{\circ}\text{C}$, RELATIVE HUMIDITY : $65 \pm 20\%$

TIEM	SPECIFICATION	TEST FREQUENCY	TEST EQUIPMENTS
IND	$8.4\text{UH} \pm 10\%$	100 KHZ/1.0V	LCRMETRTH2830N
DCR	50mΩ Max	\	PH2511S
Q	$100 \pm 10\%$	100 KHZ/1.0V	LCRMETRTH2830N

5. Coil specification

Turns	Wire Dia.	Wdg. Type Spred/Close	Wdg.Direction	Intersect Yes/Not	Coil Positive/ Anti Paste
11T S	0.08*80P (Silk-Covered Wire)	(Close)	(Anticlockwise)	(Yes)	(Anti-/Paste)

6. Bill of materials

number	Material name	Description	Material Code
1	wire rod	0.08*80P Hot air twisted wire	
2	Hard magnetic disk	G42.5*19.5*2.0H (Crown shaped magnetic disc with convex platform and groove)	
3	Adhesive	JS-E103(Thickened) White glue	
4			
5			
6			
7			